

ABSTRACT

An object of the present invention is to provide an adhesive tape for processing semiconductor wafers and the like that is able to adequately reduce the amount of adhesive remaining on the surface of an adherend after peeling off the tape. The adhesive tape for semiconductor wafer processing (100) according to the present invention comprises a base material layer (200) and an adhesive layer (300). The adhesive layer (300) is formed on at least one side of the base material layer (200). In addition, the adhesive layer (300) is mainly composed of a carboxyl group-containing polymer. The carboxyl group-containing polymer contains a radiation-polymerizable compound (and particularly, urethane acrylate).